

DISCOVERY SERIES – 2022

LEO SATELLITES – OPPORTUNITIES IN SPACE AND ON EARTH	3/22
APPLE MAC STUDIO – EMPOWER STATION	3/22
SMALL, LARGE, HUGE, CHIPLET	4/22
GLOBAL LEADING PCB COMPANIES	6/22
TV TEARDOWN: A LOOK BEHIND THE SCREENS	6/22

DISCOVERY SERIES – 2021

PERSONAL COMPUTERS: NOT AT ALL BORING	1/21
NOTHING GENTLE ABOUT A BULLWHIP: PART SHORTAGES IN THE 2021 TECH HARDWARE SUPPLY CHAIN	2/21
BEVs: ARE YOU READY FOR THE VOLTSWAGON?	6/21
GLOBAL LEADING PCB COMPANIES	6/21
BATTERIES: CHARGING AHEAD	7/21
FOLDABLE SMARTPHONES: MORE DISPLAY, MORE EVERYTHING	9/21
ADVANCED PACKAGING IN SMARTWATCHES	11/21
THERMAL INTERFACE MATERIALS	12/21
FLEX BEYOND FLEXING	12/21

DISCOVERY SERIES – 2020

CORONAVIRUS IMPACT	2/20
CORONAVIRUS IMPACT UPDATE - MARCH 27, 2020	3/20
APPLE AIRPODS PRO: GETTING CLOSER	4/20
PV REVIEW AND OUTLOOK	4/20
CORONAVIRUS IMPACT UPDATE - APRIL 30, 2020	4/20
CORONAVIRUS IMPACT UPDATE - JUNE 25, 2020	6/20
BATTERY RAW MATERIALS: A ROADBLOCK FOR ELECTRIC VEHICLES?	8/20
CORONAVIRUS IMPACT UPDATE - SEPTEMBER 30, 2020	9/20
APPLE IPHONE 12 PRO - THINK DIFFERENT	10/20
HYDROGEN ECONOMY - LONG ROAD AHEAD	11/20
MAIN DRIVER OF PCB GROWTH: PACKAGE SUBSTRATES	12/20
CORONAVIRUS IMPACT UPDATE - DECEMBER 22, 2020	12/20

DISCOVERY SERIES – 2019

FLAGSHIP SMARTPHONES	1/19
HAPTIC TOUCH	3/19
PHOTOVOLTAICS UPDATE	3/19
APPLE AIRPODS 2 - FAR FROM FINAL	5/19
5G - THE FUTURE HAS ARRIVED	5/19
AUTOMOTIVE ELECTRONICS – FAHRVERGNÜGEN ONLY FOR SOME	9/19
THE US-CHINA TRADE WAR – TARIFFS AND UNCERTAINTIES THAT BURDEN THE ELECTRONICS INDUSTRY	11/19
LED LIGHT BULBS	12/19
MOBILE PHONES - IT'S NOT OVER YET	12/19

DISCOVERY SERIES – 2018

ELECTRIC VEHICLES: A GROWTH DRIVER FOR THE ELECTRONICS INDUSTRY?	2/18
ELECTRONICS AT RISK: PROTECTING VULNERABLE SYSTEMS	3/18
PV REVIEW AND OUTLOOK	3/18
CHINA'S IMPACT ON THE PV MARKET	6/18
SMART HOMES	6/18
MICROLEDs	7/18
MUCH BETTER REALITY BEYOND THE HYPE	8/18
5G- OFF TO THE RACES	11/18
OLED DISPLAYS: PREPARE FOR TAKE-OFF	12/18
SMARTWATCHES - DOUBLING DOWN, DOUBLING UP	12/18

DISCOVERY SERIES – 2017

CHINESE SMARTPHONES	2/17
BRAINY WHEELS - SELF-DRIVING CARS	3/17
PV REVIEW AND OUTLOOK	3/17
SAMSUNG S8	4/17
STRAIGHT PATH TO 5G	5/17
SMART SPEAKERS: FAR MORE THAN VOICE	6/17
LED LIGHT BULBS	6/17

APPLE WATCH SERIES 3: SERIOUSLY DENSE	9/17
APPLE IPHONE 8: PSYCHEDELIC INSIDE	10/17
SOLID-STATE LITHIUM-ION BATTERIES: ARE WE THERE YET?	10/17
IPHONE X MARKS THE SPOT	12/17
SLPs: SUBSTRATE-LIKE PCBs APPLE DRIVES INTERCONNECT TECHNOLOGY TO THE NEXT LEVEL	12/17
DISCOVERY SERIES – 2016	
PRINTED CIRCUIT BOARDS: THE BACKBONE OF ELECTRONIC SYSTEMS	1/16
GROWTH SECTORS OF THE ELECTRONICS INDUSTRY	3/16
PV REVIEW AND OUTLOOK	3/16
UBIQUITOUS COMPUTING	4/16
POLYMERIC THERMAL INTERFACE MATERIALS (TIM)	6/16
DASHING HEARABLES	6/16
ELECTRONICS IN INDIA	8/16
IT'S NEVER ENOUGH	9/16
BATTERY SAFETY: A HOT TOPIC	10/16
SENSORS: ELECTRONICS MEETS THE REAL WORLD	12/16
WAFER –BASED PACKAGING: COMING OF AGE	12/16
DISCOVERY SERIES – 2015	
ELECTRONICS INDUSTRY OUTLOOK: MATURATION OF RECENT DRIVERS	3/15
PV REVIEW AND OUTLOOK	3/15
APPLE WATCH	4/15
RE-INVENTING THE LIGHT BULB	6/15
ALTERNATIVES TO SUBSTRATE-BASED ARRAY PACKAGES	8/15
INTERNET OF THINGS	9/15
APPLE IPHONE 6S – TIC TOC	10/15
5G - NEXT GENERATION IN CELLULAR COMMUNICATIONS	11/15
ELECTRONIC MATERIALS REPORTER	12/15
FUTURE COMPUTING	12/15
DISCOVERY SERIES – 2014	
ELECTRONICS INDUSTRY OUTLOOK	3/14
MORE CHIC, LESS NERDY: WEARABLE ELECTRONICS	3/14
PV REVIEW AND OUTLOOK	3/14
ALTERNATIVE PC TECHNOLOGIES	5/14
SOLID-STATE LIGHTING	7/14
SENSATIONAL SURROUND SENSING	8/14
MOBILE PAYMENT SYSTEMS	10/14
GRID ENERGY STORAGE	11/14
DATA CENTER HEADWINDS	12/14
METALS RECYCLING	12/14
DISCOVERY SERIES – 2013	
GRAPHENE: MIRACLE MATERIAL OR CARBON CURIOSITY?	2/13
PV 2012 REVIEW AND OUTLOOK	3/13
ELECTRONICS INDUSTRY OUTLOOK – THE NEW NORMAL	3/13
LITHIUM-ION BATTERIES	4/13
THERMAL INTERFACE MATERIAL (TIM)	6/13
3D PRINTING AND THE ART OF DISTRIBUTIVE REPLICATION	7/13
TIME TO BE FLEXIBLE	8/13
GOOD ENOUGH IS JUST RIGHT	9/13
TIC TOQ, UNRIPE TOMATOES AND SMARTWATCHES	12/13
REVISITING THE MODULE BUSINESS	12/13
DISCOVERY SERIES – 2012	
WAFER LEVEL PACKAGING	1/12
PHOTOVOLTAICS: 2011 REVIEW AND OUTLOOK FOR 2012	2/12
THE NEW iPad: SIMPLY RESOLUTIONARY	3/12
MOBILE BROADBAND BASE STATION NETWORKS: DEALING WITH 20-FOLD INCREASE IN DATA TRAFFIC	4/12
SEMICONDUCTOR PACKAGING ROADMAPS	7/12
PICTURING THE FUTURE OF THE PRINTED CIRCUIT INDUSTRY	9/12
ULTRABOOKS: ULTRA RESPONSIVE. ULTRA SLEEK	9/12

IPHONE 5: UNDER-COVER OVER-ACHIEVER	10/12
C-SI TECHNOLOGY	11/12
CHINESE SMARTPHONES	11/12
DISCOVERY SERIES – 2011	
HURRAHING IN HARVEST	2/11
THE CHALLENGES OF SEMICONDUCTOR TECHNOLOGY FOR BEYOND 22nm	2/11
PHOTOVOLTAICS: 2010 REVIEW AND OUTLOOK FOR 2011	3/11
THE PRINTED CIRCUIT INDUSTRY REDUX	5/11
TIME TO TUNE (EXCERPT FROM THE WIRELESS TECHNOLOGY REPORT, JUNE 2011)	7/11
LED LIGHTING: CONFINING LIGHT INTO A CHANNEL PART 1	8/11
PHOTOVOLTAICS: THE LONG-TERM OUTLOOK	8/11
EDUCATING THE POWER GRID	8/11
LED LIGHTING: CONFINING LIGHT INTO A CHANNEL PART 2	9/11
IMAGE SENSORS: CONTINUED STRONG GROWTH THROUGH A BROADENING ARRAY OF APPLICATIONS	9/11
LITHIUM BATTERIES	12/11
AMAZON KINDLE FIRE	12/11
DISCOVERY SERIES – 2010	
PHOTOVOLTAICS MARKET REVIEW AND OUTLOOK	3/10
THE NEW ERA IN MOBILE PHONES	3/10
ELECTRONICS INDUSTRY FORECAST 2009 – 2014	3/10
APPLE IPAD – A WHOLE NEW EXPERIENCE	4/10
"BLUETOOTH" FOR POWER	7/10
TRAFFIC TSUNAMI	8/10
YOUR LIFE IN 3D	9/10
NEW SURFACE FINISHES FOR ROHS	11/10
KINECTING HUMANS AND MACHINES	11/10
MODULE-LEVEL POWER CONVERSION DEVICES FOR PHOTOVOLTAIC MODULES	12/10
DISCOVERY SERIES – 2009	
PHOTOVOLTAICS MARKET STATUS AND OUTLOOK	1/09
THE HIGH-BRIGHTNESS LED OPPORTUNITY TRANSITIONING FROM COMPONENT TO SYSTEM	1/09
AMAZON KINDLE 2	3/09
THERMAL INTERFACE MATERIALS: THE CONDUIT TO COOLER DEVICES	3/09
FUEL CELLS	4/09
BULLWHIPS AND SUPPLY CHAINS, FISCALLY STIMULATING ACTIVITY, AND NEW GROWTH PROSPECTS	4/09
PRINTED CIRCUIT INDUSTRY DYNAMICS: RETROSPECTIVE AND OUTLOOK	6/09
PALM PRE: IPHONE KILLER?	6/09
AN OVERVIEW OF 3D DISPLAYS	7/09
THE MAGNETIC COMPONENT BUSINESS	8/09
HIGH POWER LED PACKAGING	12/09
DISCOVERY SERIES – 2008	
MARKET DYNAMICS IN THE PHOTOVOLTAICS INDUSTRY	1/08
RECHARGEABLE BATTERIES	3/08
SILICON-ON-INSULATOR TECHNOLOGY	4/08
TOUCHSCREEN TECHNOLOGY	5/08
ENVIRONMENTAL DIRECTIVES	6/08
APPLE IPHONE 3G RELOADED	7/08
PRECIOUS METALS IN ELECTRONICS	7/08
HITACHI CABLE'S ACQUISITION OF CASIO MICRONICS' COF DIVISION	8/08
MEMS MANUFACTURING	11/08
HIGHER AND HIGHER – 4G MOBILE BROADBAND SERVICES	12/08
THE MIDDLE EAST: A GROWTH MARKET FOR ELECTRONICS	12/08
DISCOVERY SERIES – 2007	
UNDERSTANDING THE MODULE BUSINESS	1/07
APPLE IPHONE - FIRST TOUCH, PART 1	2/07
DIGITAL CAMCORDERS	2/07
TECHNOLOGY FORECAST AND IMPACT ANALYSIS OF PCB EMBEDDED COMPONENTS	3/07
THE STATUS OF ORGANIC ELECTRONICS	4/07
APPLE IPHONE – FINAL TOUCH	8/07

UMPC	9/07
IPTV AND AT&T'S CHALLENGES	10/07
ELECTRONIC MATERIALS – STILL THE PLACE TO BE	11/07
EXPLOSIVE TRACE DETECTION SYSTEMS	11/07
INDIA'S ELECTRONICS INDUSTRY–OPPORTUNITIES AND CHALLENGES	12/07
3D THROUGH-SILICON VIA TECHNOLOGY	12/07
 DISCOVERY SERIES – 2006	
STORAGE TECHNOLOGY: SOLID-STATE MEMORY, HARD DISK DRIVES, AND OPTICAL DISKS	2/06
SiC: PATIENCE, PERSEVERANCE, PAYOFF	2/06
ANTENNA TECHNOLOGY	3/06
HANDHELD ELECTRONICS CONVERGENCE	4/06
RADIO FREQUENCY IDENTIFICATION TAGS (RFID) – LESS THAN 1¢ PER TAG OR BUST	5/06
THE NEW FRONTIER – BUSINESS OUTLOOK AND WHAT'S NEXT AFTER CHINA	6/06
CAMERA MODULE TECHNOLOGY	7/06
CURRENT TRENDS IN PHOTOVOLTAICS	11/06
SENSORS	11/06
FTTP VERSUS CABLE	12/06
PLAYSTATION 3 – LET THE GAMES BEGIN	12/06
 DISCOVERY SERIES – 2005	
ELECTRONICS MANUFACTURING CONTRACTED OUT	1/05
THE SONY PLAYSTATION 2: A FIVE-YEAR HISTORY OF ASSEMBLY AND SEMICONDUCTOR TECHNOLOGY	2/05
BIOCHIPS	3/05
YES, IT BOOMED AGAIN – NOW WHAT?	4/05
MEMS	6/05
NOVEL USER INTERFACES	7/05
CHINA, BREEDING GROUND FOR TOMORROW'S OEMS	7/05
HIGH-SPEED MANUFACTURING IN ELECTRONICS	7/05
NANOTECHNOLOGY IN ELECTRONICS	9/05
LEAD-FREE FORECAST REVISITED	9/05
FLEXIBLE PRINTED CIRCUIT BOARDS – DISPLAYING CONTINUED OPPORTUNITY FOR GROWTH	11/05
ENERGY TO GO – POWERING PORTABLE ELECTRONICS	12/05
RAW AND INDUSTRIAL MATERIALS – FEEDSTOCK FOR THE ELECTRONICS INDUSTRY	12/05
WINNING DISPLAY TECHNOLOGY	12/05
WIRELESS TECHNOLOGIES IN THE AUTOMOBILE	12/05
HIGH POWER DIE INTERCONNECT CHALLENGES	12/05
THE END OF INNOVATION IN THE ELECTRONICS INDUSTRY?	12/05
 DISCOVERY SERIES – 2004	
2004 ELECTRONICS INDUSTRY FORECAST	1/04
PLASMA DISPLAY PANELS – PICTURE PERFECT	2/04
PHOTOVOLTAICS – EVERY TECHNOLOGY FINDS A HOME	3/04
MOBILE PHONES – TRENDSETTERS IN ELECTRONICS PACKAGING	4/04
ADVANCED IMAGE SENSORS	5/04
ELECTRONICS MATERIALS – A NEED FOR NEW DEVELOPMENT MODELS	6/04
HIGH BRIGHTNESS LEDs – A BRIGHT FUTURE	7/04
HIGHLIGHTS FROM THE PRISMARK PRINTED CIRCUIT REPORT	8/04
WHERE ARE WE IN THE CURRENT CYCLE?	9/04
ELECTRIC DOUBLE-LAYER CAPACITORS (EDLCs)	10/04
AUTOMOTIVE RADAR – CRUISING AT 77 WHILE STOPPING CRASHES AT 24	10/04
TRENDS IN MEDICAL ELECTRONICS SYSTEMS	12/04
HIGHLIGHTS FROM THE PRISMARK SEMICONDUCTOR AND PACKAGING REPORT	12/04
 DISCOVERY SERIES – 2003	
THE ELECTRONICS INDUSTRY OUTLOOK FOR 2003	1/03
OUTLOOK FOR COMMUNICATIONS	2/03
THE RECHARGEABLE BATTERY COMPONENT AND MATERIALS MARKET	3/03
PHOTOVOLTAICS – CLEAR SKIES AHEAD?	3/03
ELECTRONICS RECYCLING – IF WE DON'T LEARN HOW, WE WILL ONE DAY BE MINING OUR LANDFILLS	4/03
WIRELESS INFRASTRUCTURE EQUIPMENT – A LARGE MARKET WITH SPECIAL NEEDS	4/03
THE HOLE TRUTH	4/03
THE PREMATURE DEATH OF MOORE'S LAW	5/03

<u>COMPETING IN A MATURE ELECTRONICS INDUSTRY</u>	6/03
<u>THE OUTLOOK FOR JAPANESE COMPANIES IN A MATURING ELECTRONICS INDUSTRY</u>	6/03
<u>SYSTEM IN PACKAGE (SIP): REVOLUTION OR REVIVAL</u>	7/03
<u>AUTOMOTIVE LIGHTING – ADOPTION OF NEW TECHNOLOGIES</u>	7/03
<u>JAPAN FLEXES SOME PCB MUSCLE</u>	9/03
<u>BEING A COMPETITIVE ELECTRONIC MATERIALS SUPPLIER IN A CHANGED INDUSTRY</u>	11/03
<u>HEARING THINGS IN AN UNTAPPED WORLD</u>	11/03
<u>RFID TAGS – IDENTIFYING THE OPPORTUNITIES</u>	11/03
<u>WAFER LEVEL 3-D INTEGRATION – BUILDING A BETTER SOC (SYSTEM-ON-CHIP)</u>	12/03
<u>EMI SHIELDING – IT’S A MATERIAL WORLD</u>	12/03
<u>DSP/BASEBAND PROCESSOR PACKAGING TECHNOLOGIES</u>	12/03
<u>IMAGE SENSOR PACKAGING – SEEING THE FUTURE</u>	12/03